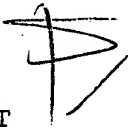




2827



PATENT  
8013-1147

**IN THE U.S. PATENT AND TRADEMARK OFFICE**

In re application of:

Hirokazu HONDA

Confirmation No. 7187

Serial No. 09/678,609

GROUP 2827

Filed October 4, 2000

Examiner David E. Graybill

MULTILAYER INTERCONNECTION BOARD, SEMICONDUCTOR  
DEVICE HAVING THE SAME, AND METHOD OF FORMING  
THE SAME AS WELL AS METHOD OF MOUNTING THE  
SEMICONDUCTOR CHIP ON THE INTERCONNECTION BOARD

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

May 11, 2004

Sir:

In response to the Official Action of December 16,  
2003, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing  
of claims that begins on page 2 of this paper.

**Remarks** begin on page 14 of this paper.